

ABSTRACT

A method of producing filled bakery products, consisting of a wafer-like crisp envelope and a creamy filling, on an industrial scale, which method comprises the steps of spreading a wafer batter into a layer 0.5
5 to 5 mm thick and adjusting its moisture content to 15-30%, thereby to provide a dough sheet that is plastically deformable and can be processed mechanically, from which an envelope is formed for said filling that is being then baked in an oven at 150-250°C for 15-30
10 seconds to provide a continuous tubular filled blank, in which the envelope has a moisture content of 3-8%, being typical of wafer, and which is then cut up transversely to provide cuttings that form said filled bakery products.

(Fig. 4)

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